

# TF2183(4)M

## Half-Bridge Gate Driver

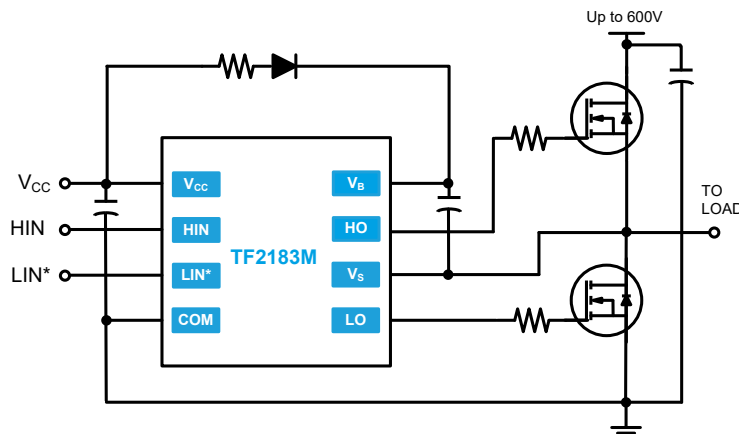
### Features

- Floating high-side driver in bootstrap operation to 600V
- Drives two N-channel MOSFETs or IGBTs in a half bridge configuration
- 1.9A source / 2.3A sink output current capability
- Outputs tolerant to negative transients
- Internal dead time of 400ns to protect MOSFETs
- Wide low side gate driver supply voltage: 10V to 20V
- Logic input (HIN and LIN\*) 3.3V capability
- Schmitt triggered logic inputs with internal pull down
- Undervoltage lockout for high and low side drivers
- Extended temperature range: -40°C to +125°C

### Applications

- DC-DC Converters
- AC-DC Inverters
- Motor Controls
- Class D Power Amplifiers

### Typical Application



### Description

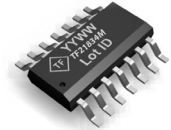
The TF2183(4)M is a high voltage, high speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. TF Semiconductor's high voltage process enables the TF2183(4)M's high side to switch to 600V in a bootstrap operation.

The TF2183(4)M logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. TF2183(4)M has a fixed internal deadtime of 400ns (typical).

The TF2183M is offered in an SOIC-8(N) package and the TF21834M is offered in an SOIC-14(N) package and operates over an extended -40 °C to +125 °C temperature range.



SOIC-8(N)

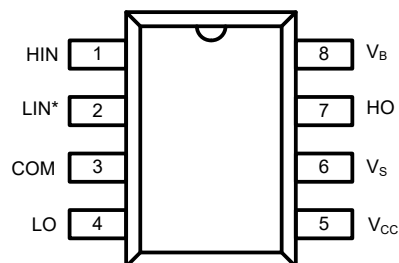


SOIC-14(N)

### Ordering Information

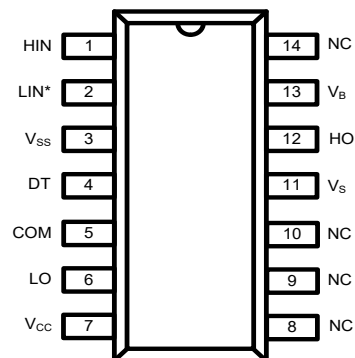
PART NUMBER	PACKAGE	PACK / Qty	Year	Year	Week	Week
			Year	Year	Week	Week
TF2183M-TAU	SOIC-8	Tube / 100	TF	YY	WW	TF2183M Lot ID
TF2183M-TAH	SOIC-8	T&R / 2500				
TF21834M-TUU	SOIC-14	Tube / 100	TF	YY	WW	TF21834M Lot ID
TF21834M-TUH	SOIC-14	T&R / 2500				

## Pin Diagrams



**Top View: SOIC-8**

**TF2183M**



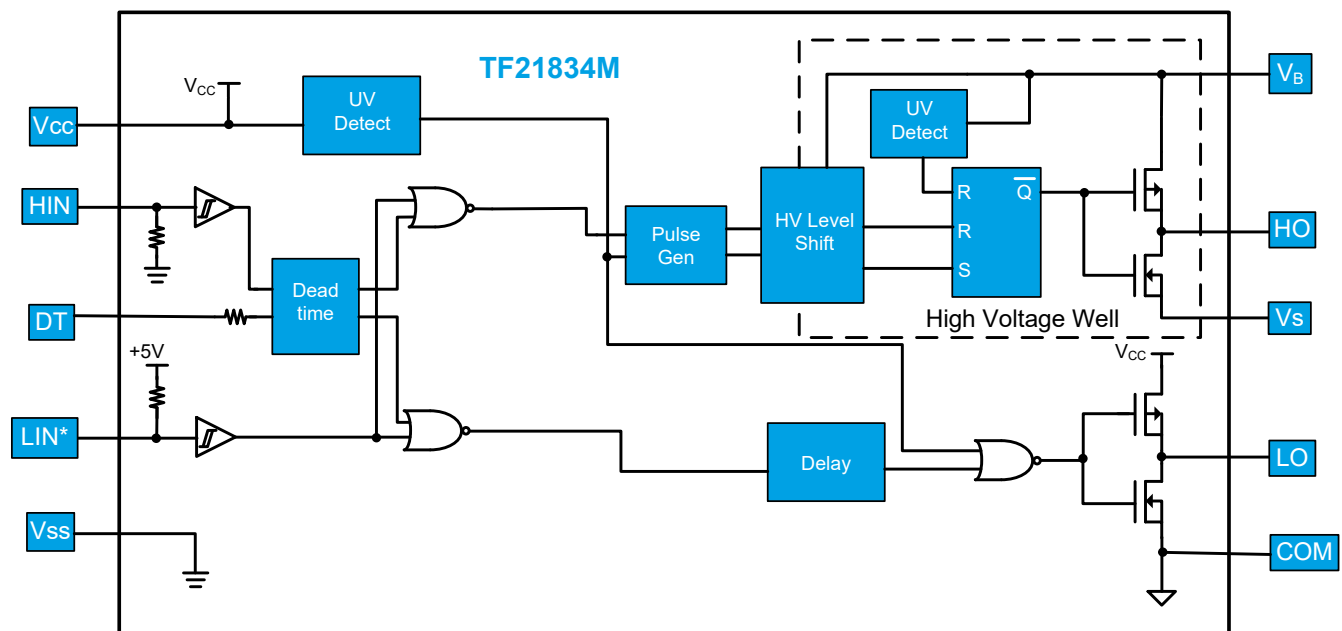
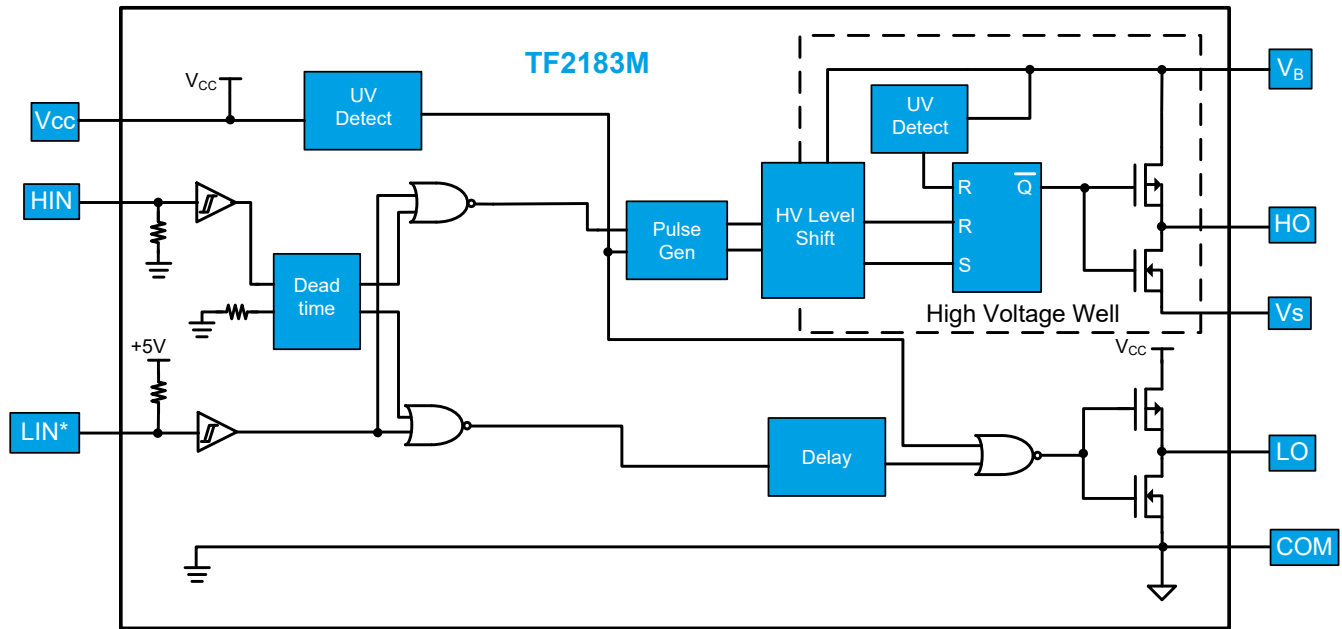
**Top View: SOIC-14**

**TF21834M**

## Pin Descriptions

PIN NAME	TF2183M Pin	TF21834M Pin	PIN DESCRIPTION
HIN	1	1	Logic input for high-side gate driver, in phase with HO.
LIN*	2	2	Logic input for low-side gate driver, out of phase with LO.
COM	3	5	Low-side and logic return (TF2183M).
LO	4	6	Low-side gate drive output.
V <sub>CC</sub>	5	7	Low-side and logic fixed supply.
V <sub>S</sub>	6	11	High-side floating supply return.
HO	7	12	High-side gate drive output.
V <sub>B</sub>	8	13	High-side floating supply.
V <sub>SS</sub>		3	Logic return.
DT		4	Programmable deadtime lead, set by external resistor to VSS.

## Functional Block Diagrams



## Absolute Maximum Ratings (NOTE1)

$V_B$  - High side floating supply voltage.....-0.3V to +624V  
 $V_S$  - High side floating supply offset voltage... $V_B$ -24V to  $V_B$ +0.3V  
 $V_{HO}$  - High side floating output voltage..... $V_S$ -0.3V to  $V_B$ +0.3V  
 $dV_S/dt$  - Offset supply voltage transient.....50V/ns

$V_{CC}$  - Low-side fixed supply voltage.....-0.3V to +24V  
 $V_{LO}$  - Low-side output voltage.....-0.3V to  $V_{CC}$ +0.3V  
 $V_{IN}$  - Logic input voltage (HIN and LIN\*).....-0.3V to  $V_{CC}$ +0.3V

**NOTE1** Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

$P_D$  - Package power dissipation at  $T_A \leq 25^\circ\text{C}$   
 SOIC-8.....0.625W  
 SOIC-14.....1.0W

SOIC-8(N) Thermal Resistance **(NOTE2)**  
 $\theta_{JA}$ .....200  $^\circ\text{C/W}$   
 SOIC-14(N) Thermal Resistance **(NOTE2)**  
 $\theta_{JA}$ .....120  $^\circ\text{C/W}$

$T_J$  - Junction operating temperature.....+150  $^\circ\text{C}$   
 $T_L$  - Lead Temperature (soldering, 10 seconds).....+300  $^\circ\text{C}$   
 $T_{stg}$  - Storage temperature .....-55 to 150  $^\circ\text{C}$

**NOTE2** When mounted on a standard JEDEC 2-layer FR-4 board.

## Recommended Operating Conditions

Symbol	Parameter	MIN	MAX	Unit
$V_B$	High side floating supply absolute voltage	$V_S + 10$	$V_S + 20$	V
$V_S$	High side floating supply offset voltage	<b>NOTE3</b>	600	
$V_{HO}$	High side floating output voltage	$V_S$	$V_B$	
$V_{CC}$	Low side fixed supply voltage	10	20	
$V_{LO}$	Low side output voltage	0	$V_{CC}$	
$V_{IN}$	Logic input voltage (HIN and LIN*)	0	5	
$V_{DT}$	Programmable deadtime pin voltage	$V_{SS}$	$V_{CC}$	
$V_{SS}$	Logic ground (referenced to COM)	-5	5	$^\circ\text{C}$
$T_A$	Ambient temperature	-40	125	

**NOTE3** Logic operational for  $V_S$  of -5V to +600V.

**DC Electrical Characteristics** (NOTE4)

 $V_{BIAS} (V_{CC}, V_{BS}) = 15V, T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
$V_{IH}$	Logic "1" (HIN) and logic "0" (LIN*) input voltage	$V_{CC} = 10V$ to $20V$ <b>NOTES</b>	2.5			V
$V_{IL}$	Logic "0" (HIN) and logic "1" (LIN*) input voltage				0.8	
$V_{OH}$	High level output voltage, $V_{BIAS} - V_O$	$I_O = 0A$			1.2	
$V_{OL}$	Low level output voltage, $V_O$	$I_O = 20mA$			0.1	
$I_{LK}$	Offset supply leakage current	$V_B = V_S = 600V$			50	$\mu A$
$I_{BSQ}$	Quiescent $V_{BS}$ supply current	$V_{IN} = 0V$ or $5V$	20	60	150	
$I_{CCQ}$	Quiescent $V_{CC}$ supply current	$V_{IN} = 0V$ or $5V$	0.4	1.6	2.0	mA
$I_{IN+}$	Logic "1" input bias current	$HIN = 5V, LIN^* = 0V$		25	60	$\mu A$
$I_{IN-}$	Logic "0" input bias current	$HIN = 0V, LIN^* = 5V$			1.0	
$V_{BSUV+}$	$V_{BS}$ supply under-voltage positive going threshold		8.0	8.9	9.8	V
$V_{BSUV-}$	$V_{BS}$ supply under-voltage negative going threshold		7.4	8.2	9.0	
$V_{CCUV+}$	$V_{CC}$ supply under-voltage positive going threshold		8.0	8.9	9.8	
$V_{CCUV-}$	$V_{CC}$ supply under-voltage negative going threshold		7.4	8.2	9.0	
$I_{O+}$	Output high short circuit pulsed current	$V_O = 0V, PW \leq 10\ \mu s$	1.4	1.9		A
$I_{O-}$	Output low short circuit pulsed current	$V_O = 15V, PW \leq 10\ \mu s$	1.7	2.3		

**NOTE4** The  $V_{IH}$ ,  $V_{IL}$ , and  $I_{IN}$  parameters are applicable to the two logic input pins: HIN and LIN\*. The  $V_O$  and  $I_O$  parameters are applicable to the respective output pins: HO and LO

**NOTES** For optimal operation, it is recommended that the input pulse (to HIN and LIN\*) should have an amplitude of 2.5V minimum with a pulse width of 800ns minimum.

## AC Electrical Characteristics

$V_{BIAS} (V_{CC}, V_{BS}) = 15V$ ,  $C_L = 1000pF$ , and  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
$t_{on}$	Turn-on propagation delay	$V_S = 0V$		180	270	ns
$t_{off}$	Turn-off propagation delay	$V_S = 0V$ or $600V$		220	330	
$t_{DM}$	Delay matching				50	
$t_r$	Turn-on rise time			40	60	
$t_f$	Turn-off fall time			20	35	
$t_{DT}$	Deadtime: $t_{DT\ LO-HO}$ & $t_{DT\ HO-LO}$	$R_{DT} = 0\Omega$	280	400	520	$\mu\text{s}$
		$R_{DT} = 200k\Omega$ (TF21834)	4	5	6	
$t_{DTM}$	Deadtime matching: $t_{DT\ LO-HO} - t_{DT\ HO-LO}$	$R_{DT} = 0\Omega$		0	50	ns
		$R_{DT} = 200k\Omega$ (TF21834)		0	600	

# Timing Waveforms

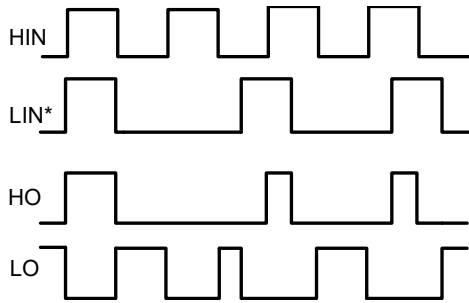


Figure 1. Input / Output Timing Diagram

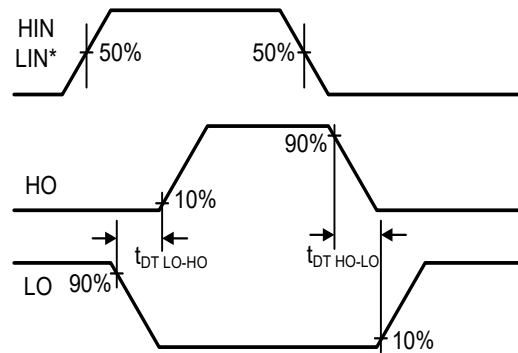


Figure 2. Deadtime Waveform Definitions

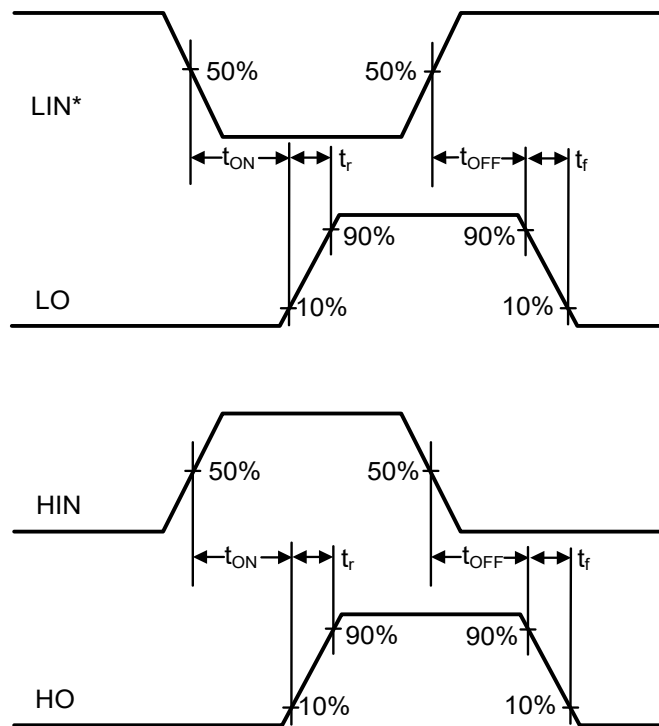
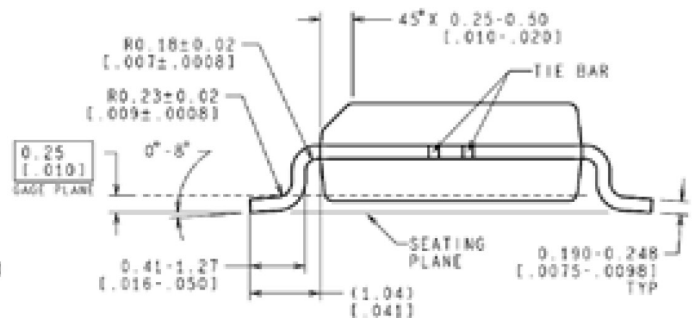
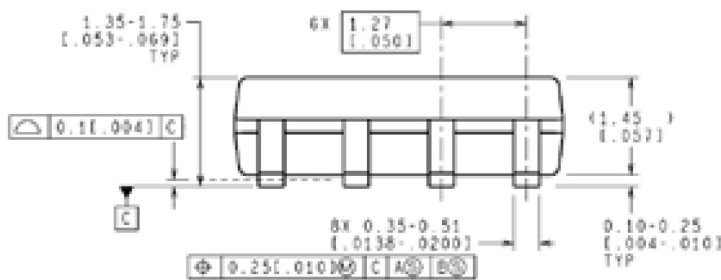
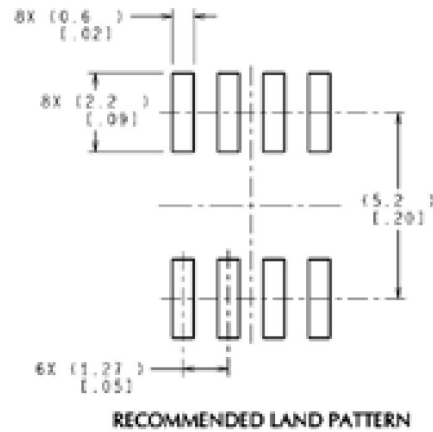
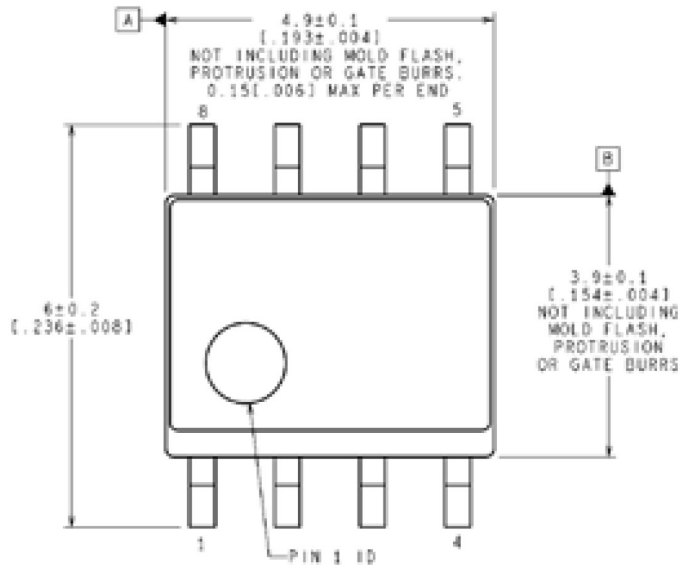


Figure 3. Switching Time Waveform Definitions

# Package Dimensions (SOIC-8 N)

Please contact support@tfsemi.com for package availability.



NOTES: UNLESS OTHERWISE SPECIFIED

1. REFERENCE JEDEC REGISTRATION MS-012, VARIATION AA.

CONTROLLING DIMENSION IS MILLIMETER  
VALUES IN [ ] ARE INCHES  
DIMENSIONS IN ( ) FOR REFERENCE ONLY



## Revision History

Rev.	Change	Owner	Date
1.0	First release, AI datasheet	Keith Spaulding	7/15/2022

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